

# Thick Film Chip Resistors, High Voltage



STANDARD ELECTRICAL SPECIFICATIONS						
MODEL	RESISTANCE (1) ( $\Omega$ )	POWER RATING (W)	VOLTAGE RATING (V) (max.)			
CRHV1206	2M - 8G	0.300	1500			
CRHV1210	4M - 10G	0.450	1750			
CRHV2010	6M - 35G	0.500	2000			
CRHV2510	10M - 40G	0.600	2500			
CRHV2512	12M - 50G	0.700	3000			

#### **Notes**

- <sup>(1)</sup> Resistance values below 1 G $\Omega$  are calibrated at 100 V<sub>DC</sub>, and values of 1 G $\Omega$  and above are calibrated at 1000 V<sub>DC</sub>. Calibration at other voltages available upon request.
- For non-standard sizes, lower values or higher power rating requirement, contact factory

### **ELECTRICAL SPECIFICATIONS**

(Reference only: Not for all values specified. Consult factory for your size and value.)

**Resistance Range:** 2 M $\Omega$  to 50 G $\Omega$ 

Resistance Tolerance:  $\pm$  1 %,  $\pm$  2 %,  $\pm$  5 %,  $\pm$  10 %,  $\pm$  20 % Temperature Coefficient:  $\pm$  100 ppm/°C (- 55 °C to + 150 °C)

Voltage Rating: 1500 V - 3000 V

Short Time Overload: Less than  $0.5 \% \Delta R$ 

### **FEATURES**

- High voltage up to 3000 V
- Outstanding stability < 0.5 %</li>
- Flow solderable
- · Custom sizes available
- Automatic placement capability
- Available with either wraparound terminations or as a single termination flip chip
- Tape and reel packaging available
- Internationally standardized sizes
- Suitable for solderable, epoxy bondable, or wire bondable applications
- Termination: Gold, palladium silver, platinum gold, platinum silver, platinum palladium gold or solder-coated nickel barrier available
- Multiple styles, termination materials and configurations, allow wide design flexibility
- Non-magnetic terminations available
- Lead (Pb)-free version is RoHS compliant

## **MECHANICAL SPECIFICATIONS**

**Construction:** 96 % alumina substrate with proprietary cermet resistance element and specified termination material

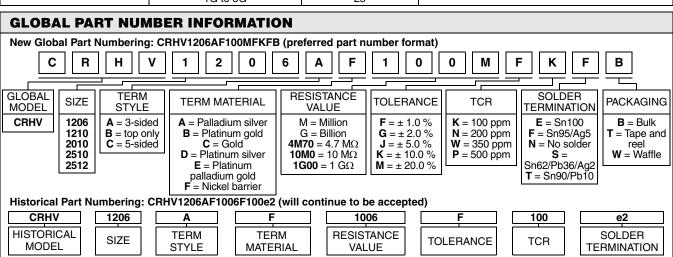
#### **ENVIRONMENTAL SPECIFICATIONS**

Operating Temperature: - 55 °C to + 150 °C

 $\textbf{Life:} \ \, \textbf{Less than 0.5 \% change when tested at full rated power } \\ \text{(Reference only: Not for all values specified. Consult factory for your } \\ \text{(Reference only: Not for all values specified.)}$ 

size and value.)

VOLTAGE COEFFICIENT OF RESISTANCE CHART					
SIZE	VALUE (Ω)	VCR (ppm/V)	FURTHER INSTRUCTIONS		
CRHV1206	2M to 199M	25	Values over 200M, consult factory		
CRHV1210	4M to 200M	25	Values over 200M, consult factory		
CRHV2010	6M to 99M	15	Values over 1G, consult factory		
	100M to 1G	20			
CRHV2510	10M to 99M	10	Values over 1G, consult factory		
	100M to 1G	15			
CRHV2512	12M to 999M	10	Values over 5G, consult factory		
	1G to 5G	25			

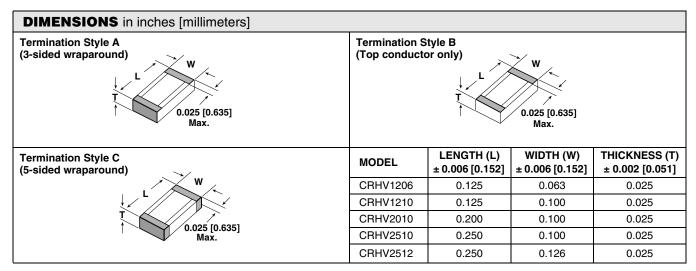


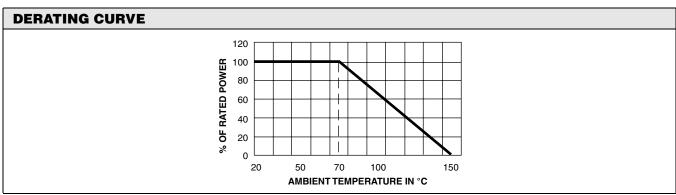
Pb containing terminations are not RoHS compliant, exemptions may apply

# Vishay Techno

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TYPE	TERMINATION MATERIAL	TERMINATION STYLE	TERMINATION STYLE/ MATERIAL CODE	SOLDER TERMINATION CODE	
Solderable	Nickel barrier	3-sided (wraparound)	AF	E, F, S, or T <sup>(3)</sup>	
	Nickel balliel	Top only (flip chip)	BF		
Wire bondable/ Solderable		3-sided (wraparound)	AE	N, F or S <sup>(1)</sup>	
	Platinum palladium gold	Top only (flip chip)	BE		
		5-sided (wraparound)	CE		
Wire bondable/ Epoxy bondable		3-sided (wraparound)	AC		
	Gold	Top only (flip chip)	BC	N	
		5-sided (wraparound)	CC		
Epoxy bondable	Palladium silver <sup>(2)</sup>	3-sided (wraparound)	AA		
		Top only (flip chip)	BA		
		5-sided (wraparound)	CA		
		3-sided (wraparound)	AB		
	Platinum gold	Top only (flip chip)	BB	N	
		5-sided (wraparound)	СВ		
		3-sided (wraparound)	AD		
	Platinum silver	Top only (flip chip)	BD		
		5-sided (wraparound)	CD		

## Notes

- (1) Use solder termination N for applications requiring wire bondable mounting, and solder terminations F or S for applications requiring solderable mounting
- (2) While not recommended, palladium silver terminations could be used for solderable applications when using a solder alloy containing silver.
- (3) Standard solder plating for the nickel barrier parts are solder terminations E or T. Hot solder dipped terminations F or S are also available.

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